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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on May 29, 2003.	
Theodore P. Cummings, Esq. 403973 Name of Attorney	Registration No.
Signature of Attorney	

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the Application of :
Stephen Paul Zimmerman, et al. : Conf. No. 3630
Serial No.: 09/851,456 : Group Art Unit: 1761
Filed: May 8, 2001 : Examiner: Drew E. Becker
Title: SNACK CHIP HAVING IMPROVED DIP CONTAINMENT AND A
GRIP REGION

DECLARATION UNDER 37 CFR 1.131

Mail Stop
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

I, Stephen Paul Zimmerman, hereby declare the following:

1. THAT I am a co-inventor of Claims 1-18 and 22-23 of the above-identified patent application;
2. THAT, prior to September, 1999, we completed the invention as described and claimed in the subject application in this country, a NAFTA country, or a WTO country, as evidenced by the following:
 - a.) Page 7 of the scientific notebook (Exhibit A) shows the triangular shape of the snack pieces;
 - b.) The curved-concave nature of the snack piece is shown in Exhibit B; and
 - c.) Specifics about the stacking of the snack pieces are shown in Exhibit C.

I, Stephen Paul Zimmerman, declare that all statements made herein are true to the best of my knowledge, or if made upon information and belief, are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

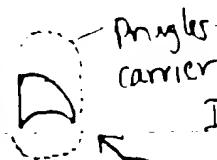
Stephen Paul Zimmerman
Stephen Paul Zimmerman
Date: *May 29, 2003*

On [REDACTED] and [REDACTED], more chips were made using the same formula and specifications given on the previous page. These chips were used in shear/use tests [REDACTED].

Chip shapes were based on specifications from the drawings below and on the next page. The chips were fired into three-dimensional shapes as follows:

Equilateral Triangle: 1) bowl-shaped

2) sinusoidal with additional curvature
(shown on the next page)



Isosceles Triangle: 1) Pringles carrier, with long axis rotated 90°

"Teardrop" / rounded triangle: 1) Pringles carrier

- measurements in millimeters

See M. Teras

88

Equilateral

- Ø 12.00

66.00

88

Isosceles

Ø 12.00

62.00

Worker's Signature

See M. Teras

Date

Corroborating Witness

See M. Teras

Date

Exhibit K

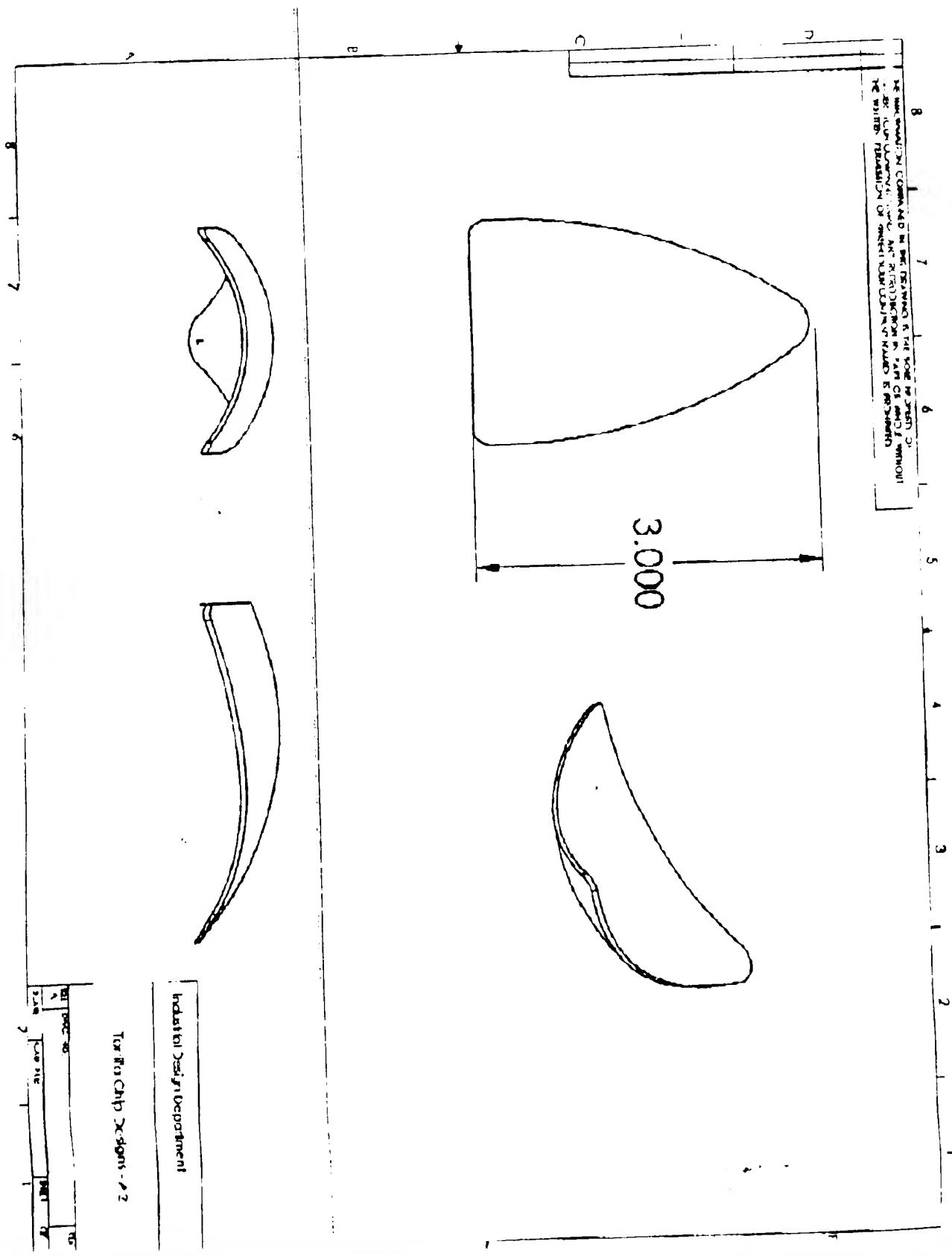


EXHIBIT C

9

Date

P&G Restricted

Subject Chip Stack Height Measurements

Chips were cut to dimensions shown on previous pages and fried in carriers of the described shape.

Equilateral Bowl

Stacks of 20 chips: Surface-to-surface

73 mm	Total Ht
70 mm	83 mm
73 mm	82 mm
63	82 mm
67	69

74	Total Ht
83 mm	82 mm
82 mm	82 mm
69	72
74	83

Sigmoid Equilateral

20 chips 64 72

78 83

67 70

redid

measurement

82

Current carrier, 90°

20 chips 64 75

63 80

63 76

77	Redid measurement
75	76
80	76

77

Current carrier, foardig

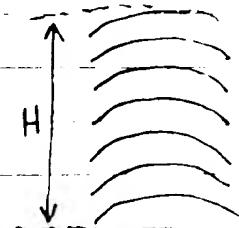
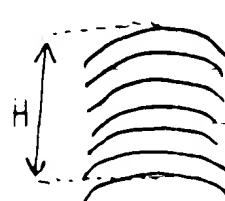
20 chips 59 78

48 65

15 chips 38 58

20 chips 56 76

- surface to surface: total ht:



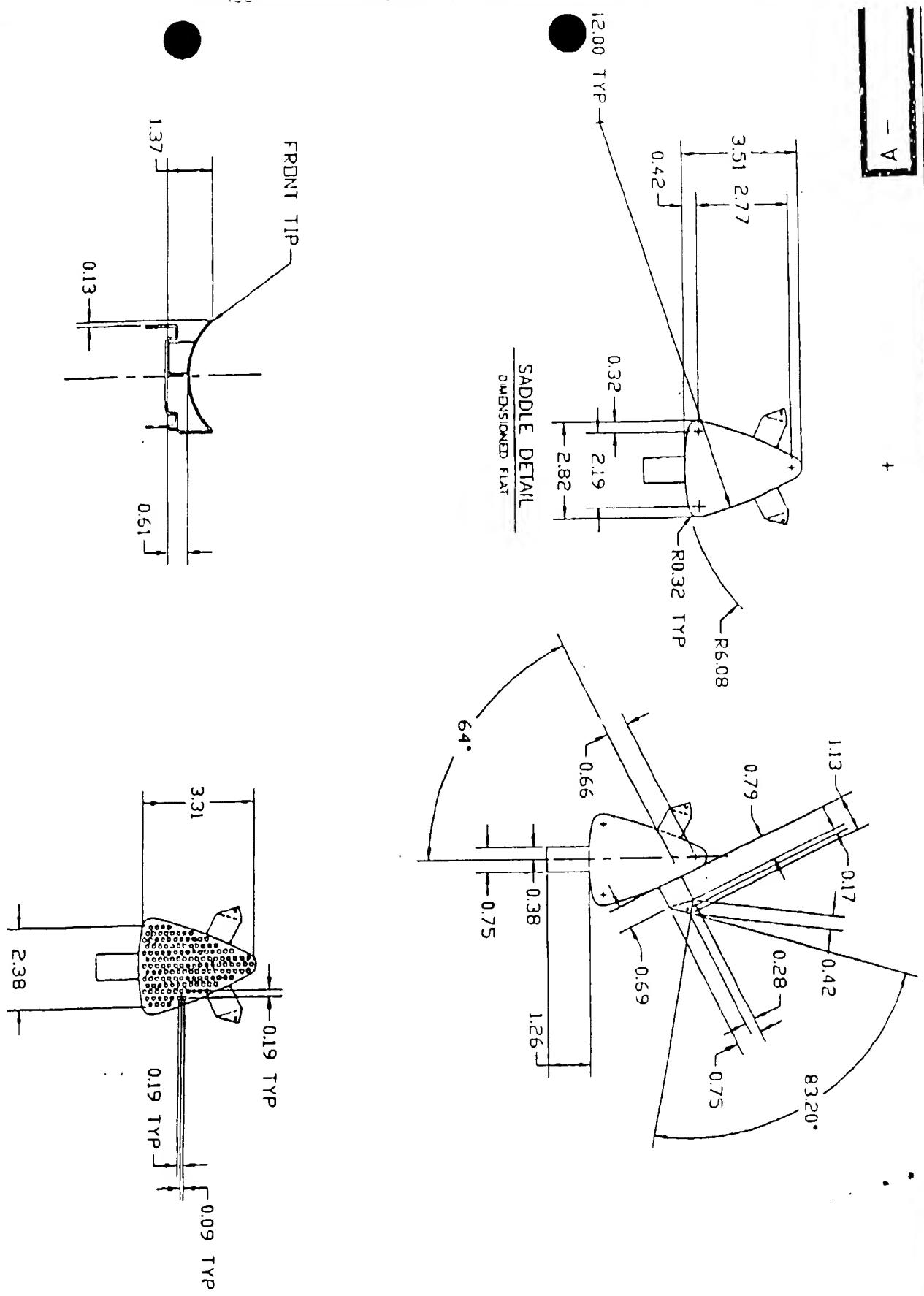
Worker's Signature

RDM Jones

Corroborating Witness

Date

Date



UNITS IN INCHES	FEET AND INCHES	INCHES
MM	MM	MM
MM	MM	MM

C

G

I

F

E

E

D

D

C

C

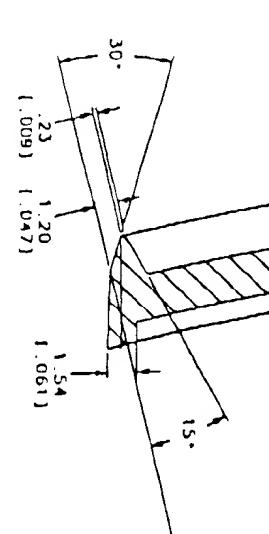
B

B

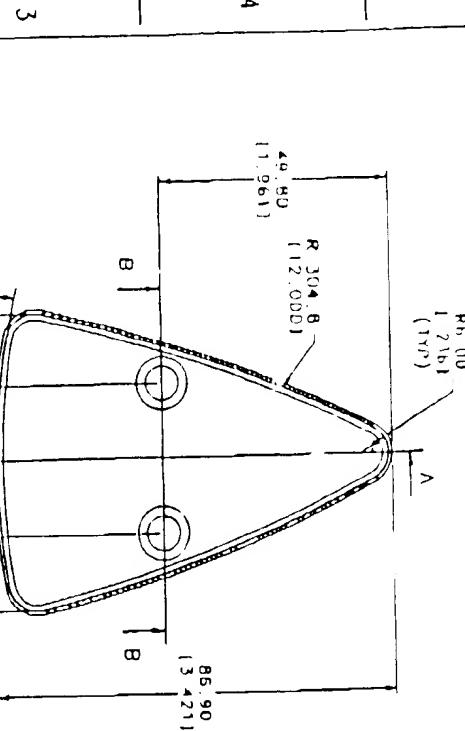
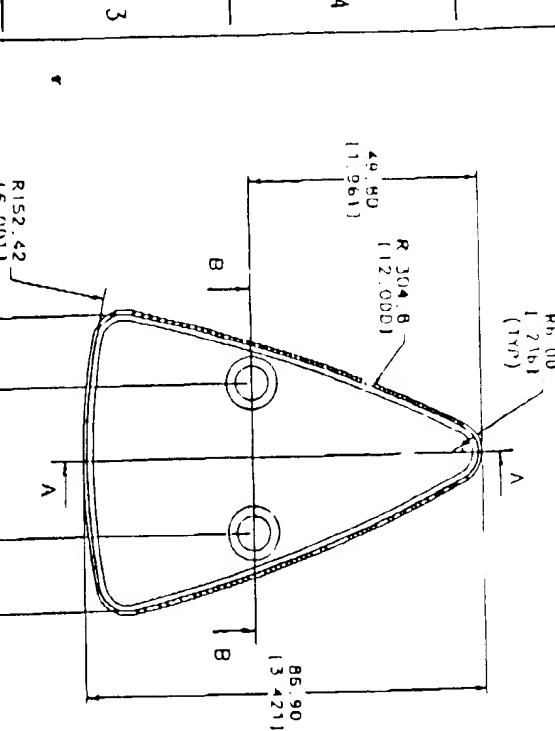
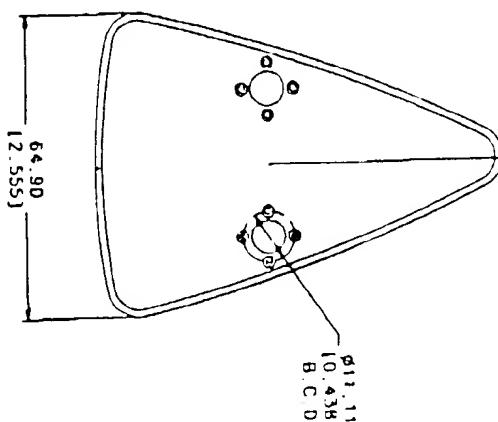
A

A

SECTION B-B

DETAIL "A"
SCALE = 4X.69 mm
.027 inch

SECTION A-A



REF ID	REV	SECTION	REV ID	SECTION	REV ID	SECTION	REV ID	SECTION
1								
2								
3								
4								
5								

1 2 3 4 5